

### 1. 封裝 Package

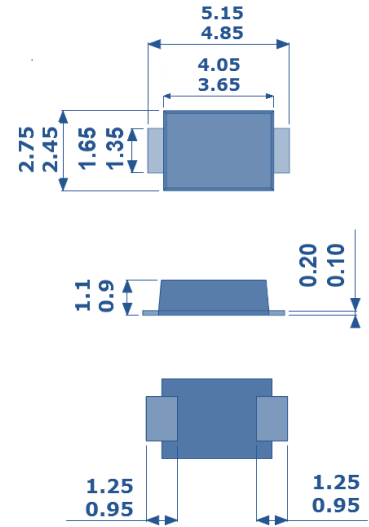
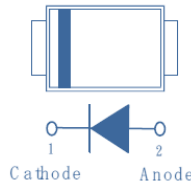
- 封裝方式 Method: SMAF
- 封裝尺寸 Dimension: 如圖示

### 2. 產品特色 Features

- For surface mounted applications in order to optimize board space
- High surge capacity
- Low power loss, high efficiency.
- Package suitable for Automated Handling
- Ultra Thin Profile Package for Space Constrained Utilization
- Meet with EU RoHS 2011/65/EU compliance
- Lead free and Green device

### 3. 機械數據 Mechanical Data

- Epoxy: UL94V-0 rated flame retardant
- Case: Epoxy, Molded
- Terminals: Solder plated solderable per MIL-STD-750 Method 2026
- Polarity: Color band denotes cathode end



單位 Unit: millimeters

### 4. 極限值與電參數 Maximum Ratings & Electrical Characteristic

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

	Symbol	SS32AF	SS34AF	SS36AF	UNITS
Marking Code	-	SS32A	SS34A	SS36A	-
Recurrent Peak Reverse Voltage	$V_{RRM}$	20	40	60	Volts
RMS Voltage	$V_{RMS}$	14	28	42	Volts
DC Blocking Voltage	$V_R$	20	40	60	Volts
Average Forward Current	$I_{F(AV)}$	3.0			Amps
Peak Forward Surge Current 8.3ms single half sine -wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	80			Amps
Forward Voltage at 3.0A	$V_F$	0.5		0.75	Volts
DC reverse current at rated DC blocking voltage $T_J=25^\circ\text{C}$	$I_R$	0.1			mA
Typical thermal resistance, Junction to Lead (NOTE1)	$R_{\theta JL}$	20			°C/W
Junction to Ambient (NOTE2)	$R_{\theta JA}$	150			
Operating Junction Temperature and Storage Temperature Range	$T_J, T_{STG}$	-55~+150			°C

Notes:

- (1) Mounted on an FR4 PCB, single-sided copper, with 48cm<sup>2</sup> copper pad area.
- (2) Mounted on an FR4 PCB, single-sided copper, mini pad.

5. 特性曲線 Rating & Characteristic Curves

Fig. 1 Forward Current Derating Curve

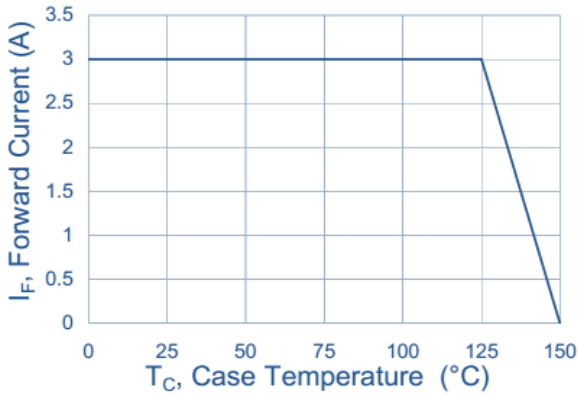


Fig. 2 Typical Reverse Characteristics

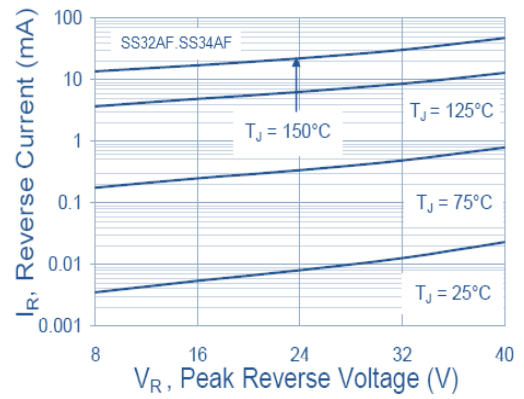


Fig. 3 Typical Reverse Characteristics

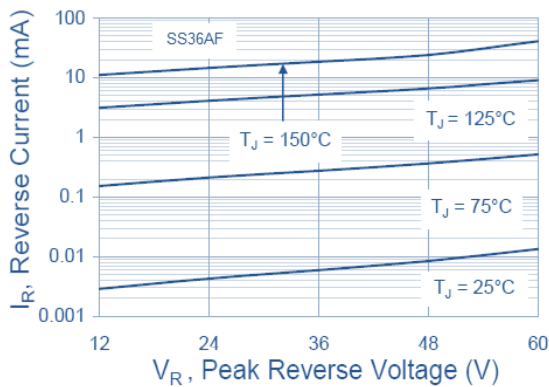


Fig. 4 Typical Forward Characteristics

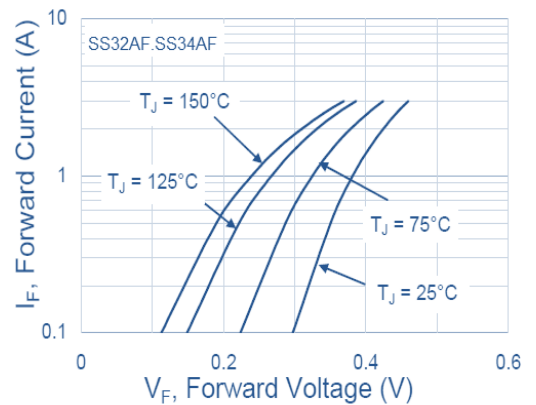
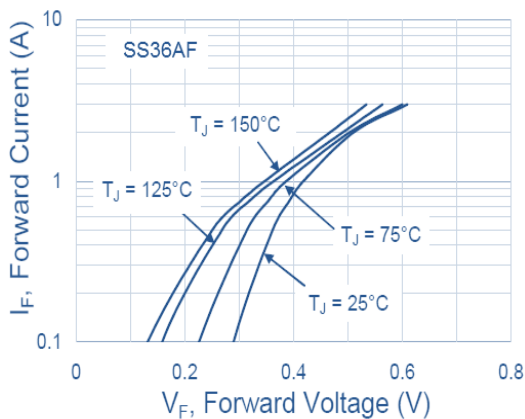
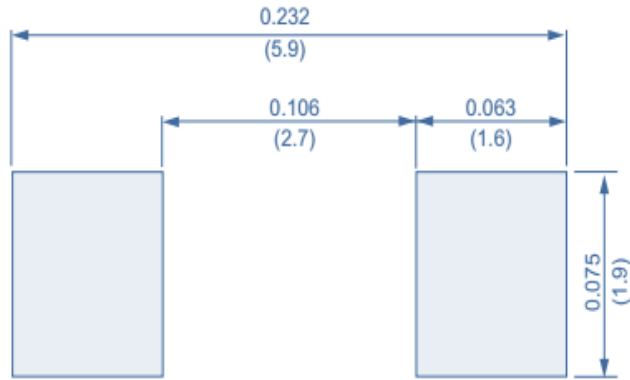


Fig. 5 Typical Forward Characteristics



Pad Layout



Unit: inch (mm)